



- [Products](#)
- [Design Resources](#)
- [Technical Info](#)
- [Global Sales](#)
- [News/Events](#)
- Useful Links---
- [RoHS](#)

Quick Reference

Search by part #

Check distributor part inventory

Stock Check

Products / BGA / Radial Fins

Radial Fin Heat Sinks for Microprocessors

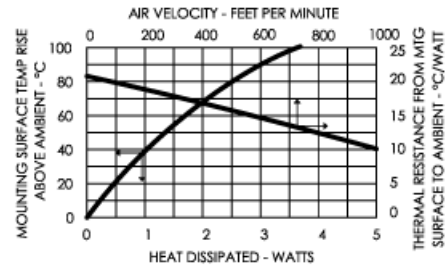
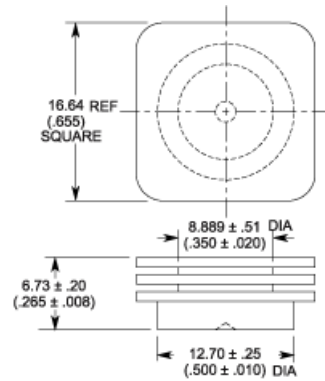
- Bond-on heat sinks for leadless chip carriers and flat packs.
- Primarily designed for 68-position devices.
- The 2283 is ideally suited to limited board space applications with high air flow.

Products

Browse Heat sinks

- By Device -
- By Product Line -
- Attachment Methods -
- Interface Materials -
- Accessories -

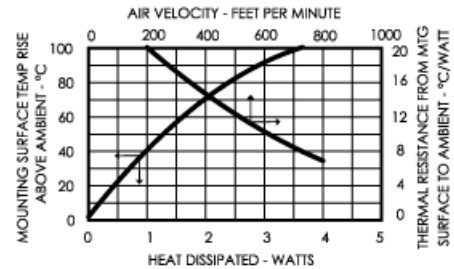
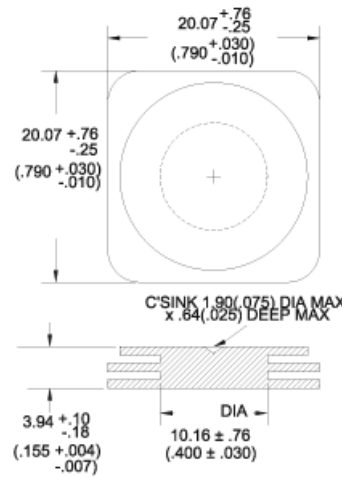
Part Number: 2283BG



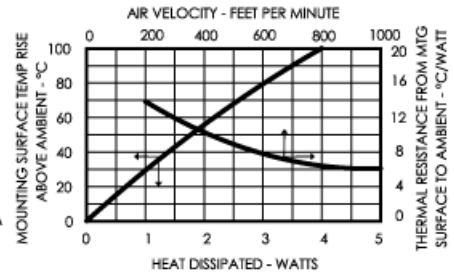
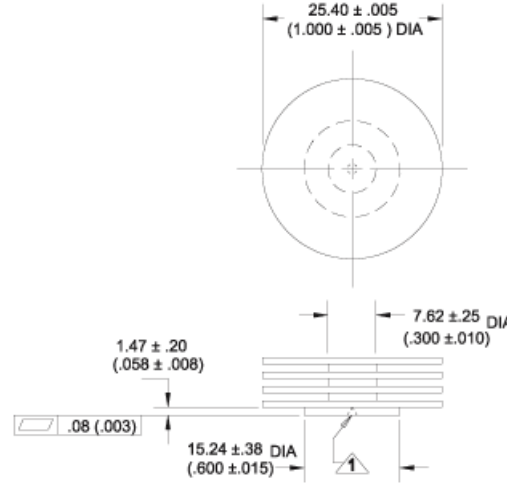
Useful Links

- [Building a part #](#)
- [Catalog Request](#)
- [Directions](#)
- [Find Distributor](#)
- [Find Sales Associate](#)
- [How to order?](#)
- [MSDS Safety Sheets](#)
- [Part # Cross Ref](#)
- [Quote Request](#)
- [RoHS Initiative](#)
- [Sample Request](#)

Part Number: 2286BG<

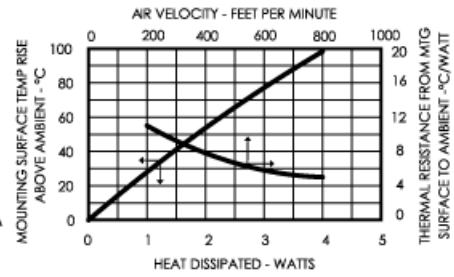
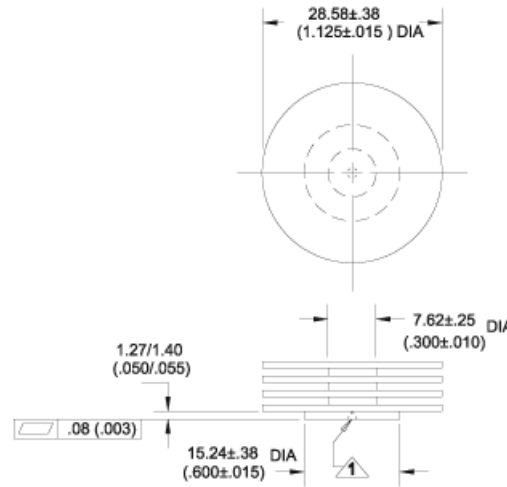


Part Number: 2288BG



Part Number: 2292BG

RoHS Compliant



Part Number: 2296BG



